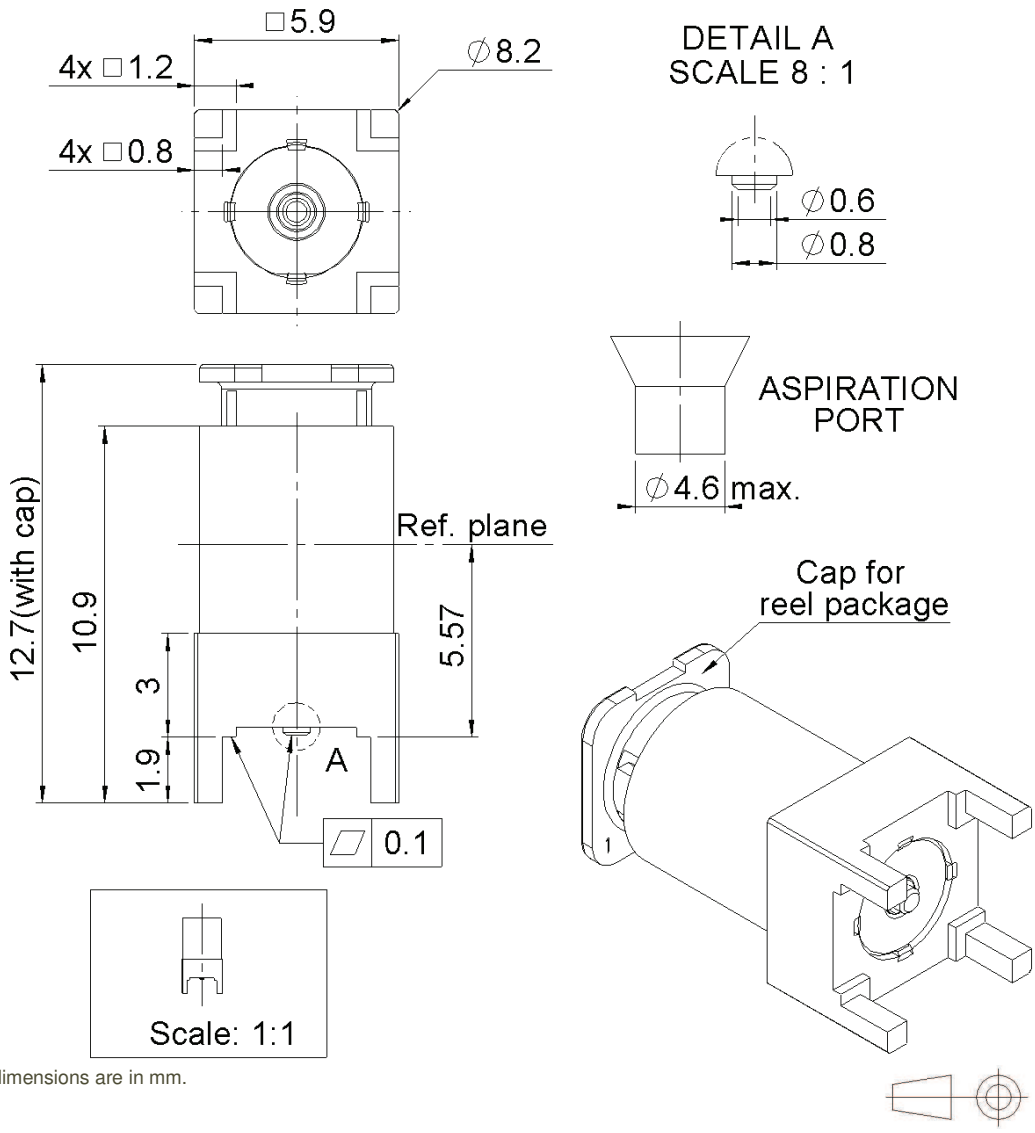


All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**NPGR**
Center contact	**BRASS**	**NPGR**
Outer contact		
Insulator	**PTFE/LCP/PEEK**	
Gasket		
Others parts	**PTFE/LCP/PEEK**	
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
350	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-6**	GHz
VSWR	**1.04***	**+**	**0.0200**	x F(GHz) Maxi
Insertion loss			**0.05***	√F(GHz) dB Maxi
RF leakage		- (	**NA**	- F(GHz)) dB Maxi
Voltage rating			**335**	Veff Maxi
Dielectric withstanding voltage			**1000**	Veff mini
Insulation resistance			**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**7**	N mini
Axial force – Opposite end	**7**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Weight	**1.4200**	g

ENVIRONMENTAL

Operating temperature	**-55/+165**	℃
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:
***Coaxial Transmission Line Only**
Power handling(typical)
>300W@2.7GHz at 25℃; >200W@2.7GHz at 85℃

SOLDER PROCEDURE

1. **Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.**

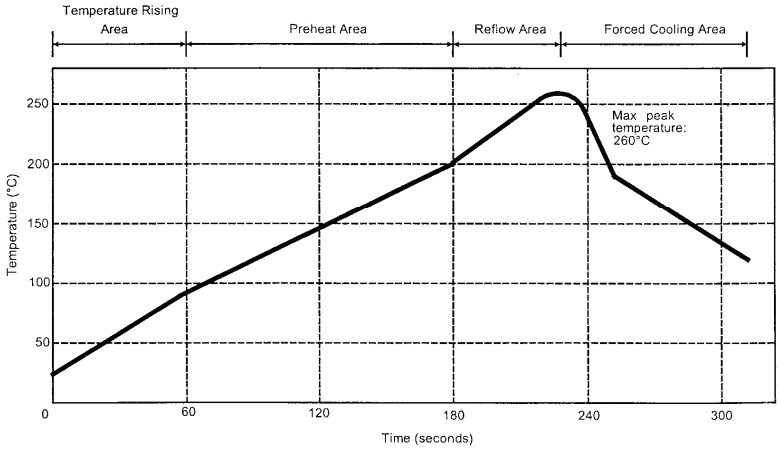
2. **Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.**

3. **This process of soldering has been tested with convection oven .Below please find, the typical profile to use.**

4. **The cleaning of printed circuit boards is not obliged.**

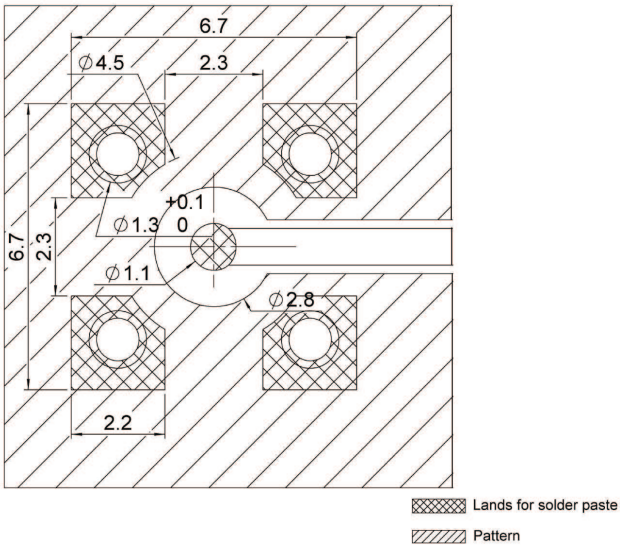
Verification of solder joints and position of the component by visual inspection.

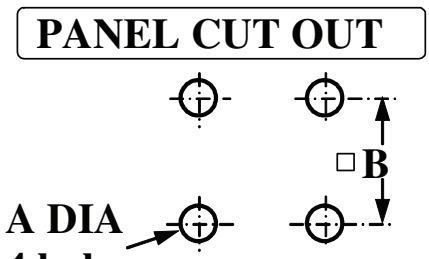
TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	℃/sec
Max Peak Temperature	260	℃
Max dwell time @260℃	10	sec
Min dwell time @235℃	20	sec
Max dwell time @235℃	60	sec
Temperature drop in cooling Area	-1 to - 4	℃/sec
Max dwell time above 100℃	420	sec

PCB





	mm	
	Maxi	mini
A	1.4	1.3
B	5.13	5.03

NOTE: Due to the potential large variation of performance depending on PCB and line parameters, we recommend the user to process a RF analyze of the connector mounted on his PCB

Shadow of receptacle for video camera